Primary (Top) Silkscreen
First (Top) Copper Layer
Primary (Top) Soldermask
Primary (Top) Pastemask

301–350 PPM
Second (Bottom) Copper Layer
301–350
SSM

Secondary (Bottom) Soldermask
SPECIFICATIONS:

MATERIAL:  - G10 OR FR-4, GLASS EPOXY .090", 1 OUNCE OF COPPER.

PROCESS:  - SMOBC.
  - MINIMUM TRACES 0.012", MINIMUM SPACING 0.012"
  - ALL HOLES ARE PLATED WITH 1 OUNCE OF COPPER.
  - MAKE SURE THE ASPECT RATIO MEET YOUR CAPABILITY.
  - DIMENSIONS FOR DRILLING ARE GIVEN AFTER PLATING.
  - DRILLING TOLERANCES ARE +/- .003"

SOLDER MASK:  - TYPE UV OR PHOTO IMAGEABLE OR EQUIVALENT.

SILKSCREEN:  - EPOXY ENAMEL WHITE.

DRILLING:  - USE 301-350.drl

DATA:  - CERBER & DRILLING FILE ARE SUPPLIED BY:
       INTEMPCO CONTROLS LTD

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301-350

FAB